

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory		User Part Number BZT52-C3V9 Part Description												
										Nexperia DHAM	Zener			
								Assembly reliability labs  Based on AEC-Q101 Test		SMD package				
Test Conditions	Duration	# Lots	# Quantity	# Rejects										
	TEST													
	Pre- and Post-Stress													
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below								
		JESD22-A113 Bake Tamb = 125 °C	24 hours											
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours											
# A1	Preconditioning	Reflow soldering	3 cycles	810	58300	0								
		MIL-STD-750-1												
	HTRB	M1038 Method A												
# B1	Bias	Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	120	11040	0								
# DI	Did3		1000 nours	138	11040	U								
		MIL-STD-750-1 M1038 Method B												
	SSOP	Tj = Tjmax, Iz = 100% of max. datasheet												
# B1b	Steady State Operational	reverse current	1000 hours	20	1600	0								
	TC	JESD22-A104												
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	170	13600	0								
	•6	JESD22-A102												
# A2 alt	<b>AC</b> Autoclave	Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	96 hours	170	13600	0								
# A3 alt	Autociave	11033dic = 203 ki d (23.7 p3id)	90 110015	170	13000	U								
	НЗТRВ	JESD22-A101												
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of												
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1]</sup>	1000 hours	170	13600	0								
		MIL-STD-750 Method 1037												
	IOL	ton = toff, devices powered to insure $\Delta Tj$ =												
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	170	13600	0								
	RSH	JESD22-A111												
# C8	Resistance to Solder Heat		10 s	130	3900	0								
# 00	SD		10.5	130	3300	U								
# C10	Solderability	J-STD-002		363	3630	0								

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Zener	11040	0	0.38	2.60E+09

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